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CHIP 1310L TECHNICAL DATA

Infrared Wavelength Laserdiodechip

Structure: **index guided, single transverse mode**

Lasing wavelength: **1310 nm typ.**

Max. optical power: **5 mW typ.**

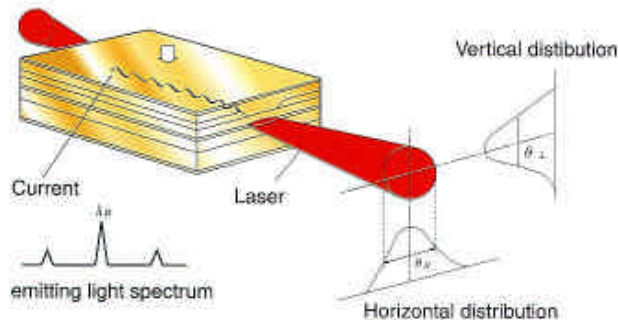
Chipsize: **300 x 300 x 100 μm [L x W x H] +/- 20 μm**

Cavity length: **300 μm +/- 5 μm**

Emitting Point Height: **1.6 - 1.8 μm from P-side**

Coating: Au coated on upper and lower side n-side: 4000 \AA , p-side: 4000 \AA

Low threshold current, low operating current, low noise



Absolute Maximum Ratings (Tc=25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Optical Output Power	P _o	5	mW
LD Reverse Voltage	V _{R(LD)}	2	V
Operation Temperature	T _C	-10 .. +50	°C
Storage Temperature	T _{STG}	-40 .. +85	°C

Optical-Electrical Characteristics (Tc = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNIT
Optical Output Power	P _o	kink free		5		mW
Emitting Aperture	A	P _o = 5 mW		1 x 2		μm^2
Threshold Current	I _{th}			10	12	mA
Operation Current	I _{op}	P _o = 5 mW		25	30	mA
Operating Voltage	V _{op}	P _o = 5 mW		1.2		V
Lasing Wavelength	λ_p	P _o = 5 mW	1280	1310	1340	nm
Beam Divergence	$\theta_{//}$	P _o = 5 mW		20		°
Beam Divergence	θ_{\perp}	P _o = 5 mW		40		°